

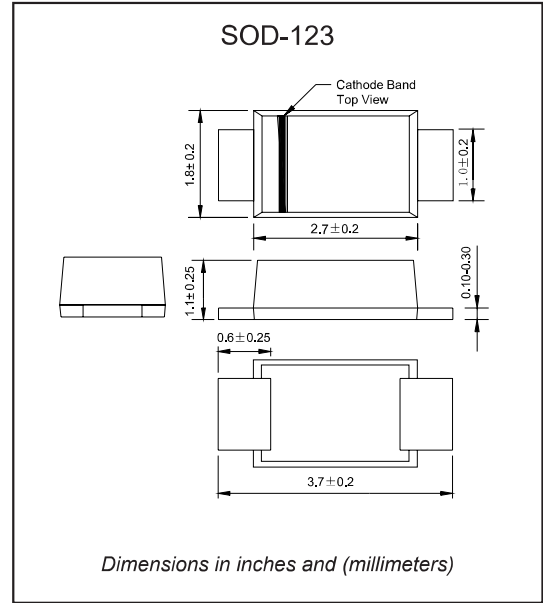
Features

- Glass passivated chip
- Built-in strain relief
- Low inductance
- High peak reverse power dissipation
- Low reverse leakage
- For use in stabilizing and clipping with high power rating
- RoHS compliant

Mechanical Data

- Case: SOD123FL Molded plastic
- Lead: Solderable per MIL-STD-750, method 2026
- Epoxy: UL 94V-0 rate flame retardant
- Polarity: Color band denotes cathode end
- Mounting position: Any

Package outline



Parameter	Symbols	Value	Unit
DC Power dissipation at TL = 75 °C ⁽¹⁾	P _D	1.0	W
Maximum forward voltage at if=200mA	V _F	1.2	V
Junction temperature range	T _J , T _{STG}	-55 to +150	°C
Storage temperature range	T _J , T _{STG}	-55 to +150	°C

Note :

(1) T_L=Lead temperature at 3/8" (9.5mm)from body

Part Number	Device Marking Code	Nominal Zener Voltage @I _T			I _{ZT} (mA)	Maximum Zener Impedance			Maximum Reverse Leakage Current		Maximum DC Zener Current
		V _{Z AVE} (V)	V _{Z MIN} (V)	V _{Z MAX} (V)		Z _{ZT MAX} (Ω) @I _{ZT}	Z _{ZK MAX} (Ω) @I _{ZK}	I _{ZK} (mA)	I _R (uA)@V _R	V _R (V)	
SML4739A	Z9V1	9.1	8.65	9.56	28.0	5.0	700.0	0.50	10.0	7.0	100.0

Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Ratings and Characteristics Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

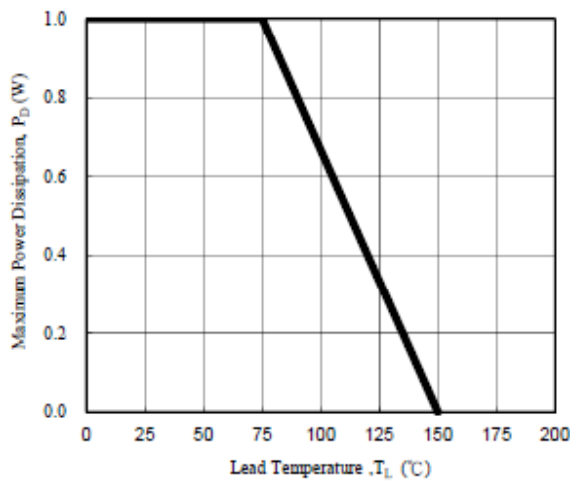


Fig. 1 - Power Temperature Derating Curve

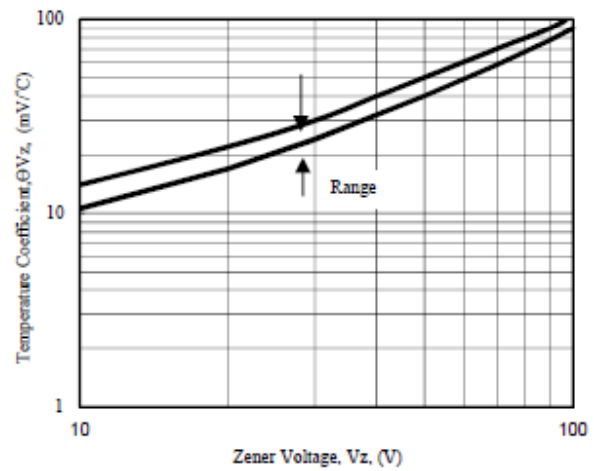


Fig. 2 - Temperature Coefficients v.s. Zener Voltage

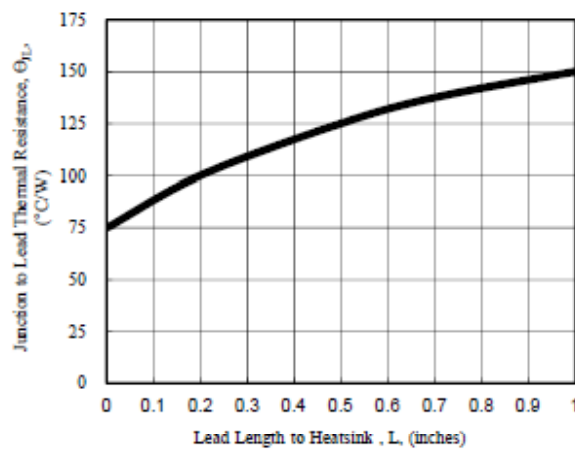


Fig. 3 - Typical Thermal Resistance v.s. Lead Length

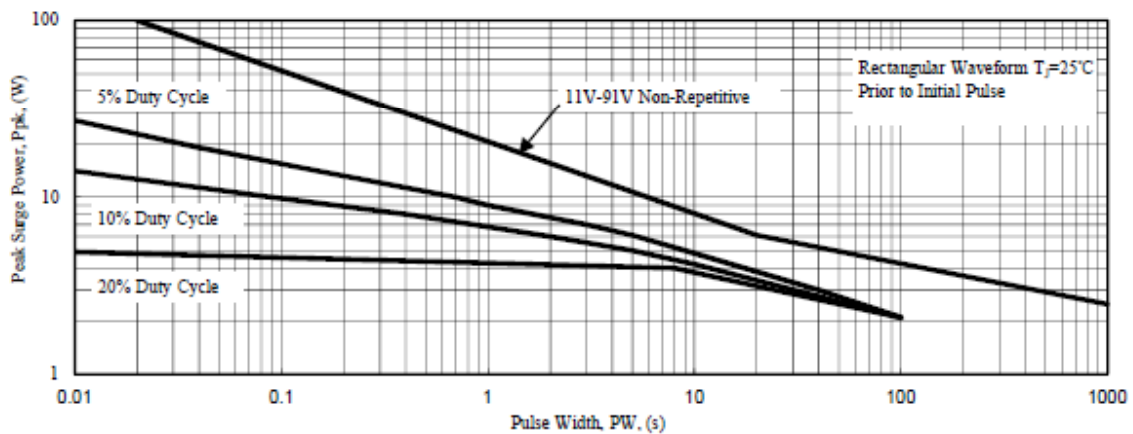


Fig. 4 - Maximum Surge Power